

MICROSTAR

MICROSTAR EH9722

Fully Automatic High-Precision Eutectic Die Bonder

EH9722 is a fully automatic eutectic die bonder for optoelectronic packaging in optical communication and data center applications. It supports dipping, eutectic, and flip chip processes, with $\pm 1.5\mu\text{m}@3\sigma$ placement accuracy. Featuring a 12-nozzle auto-change system, 8 buffer stations, and dual-gantry architecture, it enables continuous production and fast product changeover. Compatible with multiple loading methods and equipped with a streamlined software platform, EH9722 shortens setup time and improves yield.



Key Features



High Precision

Dual-gantry drive structure and high-resolution vision system deliver $\pm 1.5\mu\text{m}@3\sigma$ accuracy, meeting precision packaging needs like optical chips.



High Efficiency

12-nozzle dynamic auto-change with high-speed gantry structure enables stable high-efficiency operation; supports multiple magazine buffers to reduce loading delay.



High Flexibility

Compatible with various die sizes and packaging processes; supports multiple feeding formats to meet multi-process and multi-product production needs.



High Adaptability

Supports automatic switching of 12 nozzles, intermediate station coordination, and AGV integration for flexible process and product transitions.

Applications



Optical Module



LiDAR Sensors



RF Devices



Power Devices



Laser Radar



Microwave Devices
& Antennas

Technical Specifications

EH9722

Placement Accuracy	$\pm 1.5\mu\text{m}$ (Standard Die)	
Bonding Process	Eutectic / Dipping / UV Curing / Flip-Chip	
Equipment Efficiency	72-90 UPH(Eutectic)/180-240 UPH(Dipping)	
Angular Accuracy	$\pm 0.15^\circ$	
Application	COC/COS/COB/Flipchip/Gold-Box	
Chip Size	0.15x0.2mm-5x5mm	
Substrate Size	16x16mm	
Carrier Size	L: 160-250mm/W: 65-110mm	
Machine Dimensions	1850mmx1800mmx1850mm(L x W x H)	
Weight	2300Kg	
Bonding System	Nozzles	12 nozzles, dynamic auto-change
	Force Control	(10-100g) $\pm 2\text{g}$; (100-500g) $\pm 3\%$
Loading/Unloading System	Inline Integration	Magazine loading/unloading, AGV interface
	Barcode Function	Supports carrier barcode binding
Eutectic System	Working tables	1
	Transfer Stations	Up to 8 stations
	Heating Method	Pulse Heating
	Temperature Range	25-450°C
	Heating Rate	80 °C/s (adjustable)
Feeding Modes	Wafer	6-inch, 4 units standard
	Waffle Pack/Gel-Pak	2-inch, 18 units standard



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